HALF19 230 H19-230







Depth

HALF19 is a family of rugged servers and workstations with an aluminum construction, designed for applications that require robust and qualified MIL-GRADE equipment, suitable for operations in critical environments.

Half19-230 is a rugged display computer featuring single socket with Intel Core i processors and MXM support for AI or Maximum graphics performance of up to 6 High resolution Displays. The integrated IPMI services support monitoring, control, and management functions sending alarm notifications in case of critical events.

Half19-230 have a 2U compact modular chassis with a depth of 300mm and are provided with front brackets that make them suitable for a rack space mounting half the size of a regular 19". Two units can also be paired with a retention kit to be accommodated into a standard 19" rack.

Half19-230 rugged display computer have a layout with front I/O and rear power supply layout. The front panel includes all I/O in the front and up to 3×2.5 " drives can be mounted in a removable bay.

Half19-230 is designed to meet MIL-STD-810G for temperature and shocks, MIL-STD-167-1A for vibrations. Optionally, it can conform to MIL-STD-461 for EMI /EMC.

The I/O connectors and the power supply input can be provided with MIL-GRADE connectors upon request.

All units are delivered with their inventory list to ensure configuration control and reproducibility over time. Upon request, all server configurations can run specific thermal or mechanical environmental stress test.

Hot Swap SSD

FEATURES

- 9th Gen Intel® Core i7/i5/i3
- 2U HALF19 Workstation 300 mm depth
- Single Socket Motherboard
- 3 x 2.5" SATA/SAS SSD Front I/O connectors and rear Power Input
- Single AC Power Supply
- · Removable fan
- Optional Conformal Coating
- MIL-STD-810G Optional MIL-STD-461
- 5 years Warranty

HALF19 230 RUGGED WORKSTATION 9th Gen INTEL® Core™

TECHNICAL SPECIFICATIONS

CPU	9th Gen Intel® Core™ i7/i5/i3 LGA processor
Memory	Dual SODIMMs sockets for up to 32GB DDR4
Chipset	Intel® H310
Graphics	Dual independent displays: 2x DP++ 1.2/ 1x DVI-D/VGA Extra 4x DP 1.4 powered by MXM Modules
Network Connectivity	1x Dedicated IPMI LAN port, 2x 10 GbE ports
Storage	Up to 3 x 2.5" SATA/SAS SSD
ТРМ	1x TPM Header
Motherboard	I/O shield Available on the front: 1x COM; 1x IPMI LAN; 2x USB 2.0; 2x USB 3.2; 2x GbE; 6x Display Port
Expansion slots	1x M.2 E key supporting 1630 or 2230 for wireless LAN / Bluetooth module, 1x M.2 B key supporting 2242 or 2280 for SATA storage module 1 X MXM Module
Operative Systems	Supported: Windows© 10 IoT Enterprise 64bit,Windows© Server 2016 64bit; Windows© Server 2019 64bit; RHEL 8.4 64bit; Ubuntu, 20.04.2 LTS SVR 64bit; CentOS 7.9 64bit

POWER SUPPLY

Power Supply	AC Single Power Supply		
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MECHANICAL

Dimensions	249 (213mm body) x 88 x 300 mm (W x H x D)
Material	Aluminum with surface passivation treatment
Colour	NATO Green / RAL 6031 - Powder Coating
Mounting	2U Half of a 19" rackmount chassis; Optional Telescopic slides; Retention kit to pair two units in a 19" rackmount space included
Configuration	Front I/O - Rear Power Supply
Front Panel Leds / Buttons	Power On/Off button with LED
Drive Bays	3 x 2.5" SATA/SAS SSD
Fans	1x removable PWM fans

ENVIRONMENTAL - (DESIGN TO MEET)

Operating TemperatureStandard: 0 C / +50 C Extended: -20 C / +60 C (depending on the configurations)Operating Humidity5% to 95% non-condensed (depending on the configurations)Storage Temperature-40C / +70 C (depending on the configurations)VibrationsMIL-STD-810G, Method 514.7, Cat 4 - Proc. I - 2.24 Grms, 5-500 Hz 60 min/axis for 3 axesOperating ShockMIL-STD-810G Proc. I Method 516.7 - 15g / 11ms - half sineTransport shockMIL-STD-810G Proc. II Method 516.7 - 30g / 9ms sawtoothCertificationsDirective 2014/35/UE-LVD / Directive 2014/30/UE-EMC Directive 2011/65/UE - RoHS / Regulation (EC) No 1907/2006 - REACH		•
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	Transport shock	MIL-STD-810G Proc. II Method 516.7 - 30g / 9ms sawtooth
	Certifications	

HALF19 servers and workstations are designed in accordance with the environmental specifications indicated. Some parameters depend on the configuration. Equipment may be subjected to dedicated test profiles.